

## 1. General description

Silicon Carbide Schottky diode in a TO220-2L plastic package, designed for high frequency switched-mode power supplies.

## 2. Features and benefits

- Highly stable switching performance
- High forward surge capability  $I_{FSM}$
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

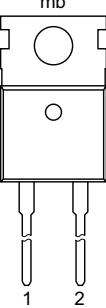
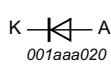
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage				650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 76$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>				A
$T_j$	junction temperature				175	°C
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 20$ A; $T_j = 25$ °C; <a href="#">Fig. 5</a>	-	1.5	1.7	V
		$I_F = 20$ A; $T_j = 150$ °C; <a href="#">Fig. 5</a>	-	1.8	2.1	V
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 20$ A; $dI_F/dt = 500$ A/ $\mu$ s; $V_R = 400$ V; $T_j = 25$ °C; <a href="#">Fig. 7</a>	-	33	-	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
GKTSC20650	TO220-2L	GKTSC206506Q	Tube	50	SOD59A	19-Mar-2015

## 7. Marking

Table 4. Marking codes

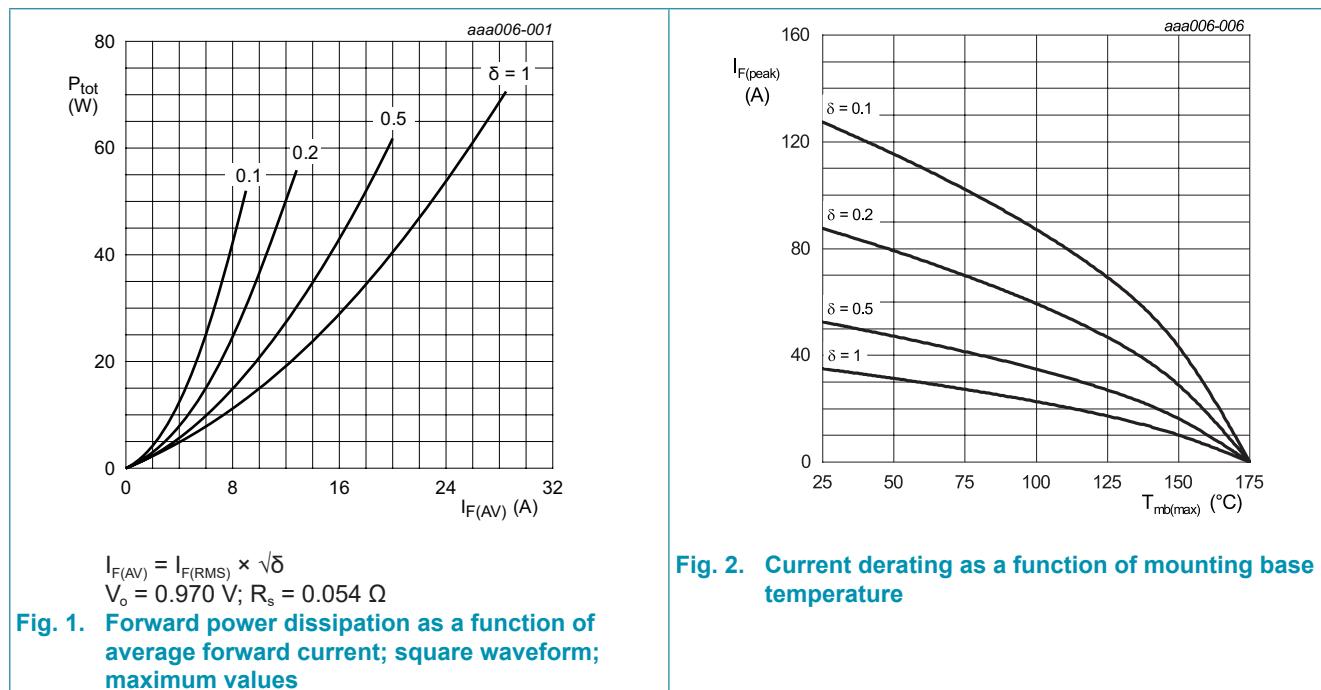
Type number	Marking codes
GKTSC20650	GKTSC 20650

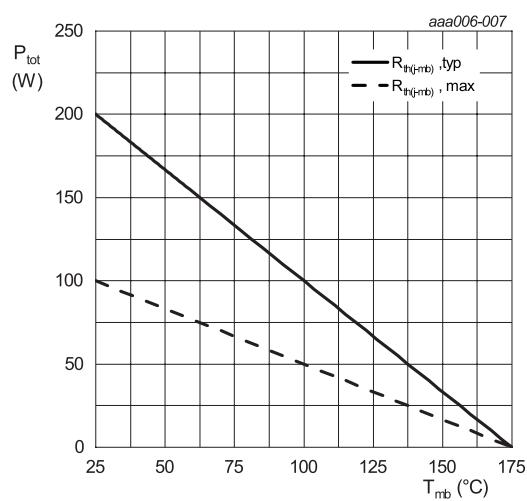
## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		650	V
$V_{RWM}$	crest working reverse voltage		650	V
$V_R$	reverse voltage	DC	650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 76^\circ\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	20	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25 \mu\text{s}$ ; $T_{mb} \leq 76^\circ\text{C}$ ; square-wave pulse	40	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10 \text{ ms}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; sine-wave pulse	100	A
		$t_p = 10 \mu\text{s}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; square-wave pulse	900	A
$I^2t$	$I^2t$ for fusing	sine-wave pulse; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 10 \text{ ms}$	50	$\text{A}^2\text{s}$
$T_{stg}$	storage temperature		-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature		175	$^\circ\text{C}$





**Fig. 3. Total power dissipation as a function of mounting base temperature**

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	with heatsink compound; Fig. 4		-	0.75	1.5	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

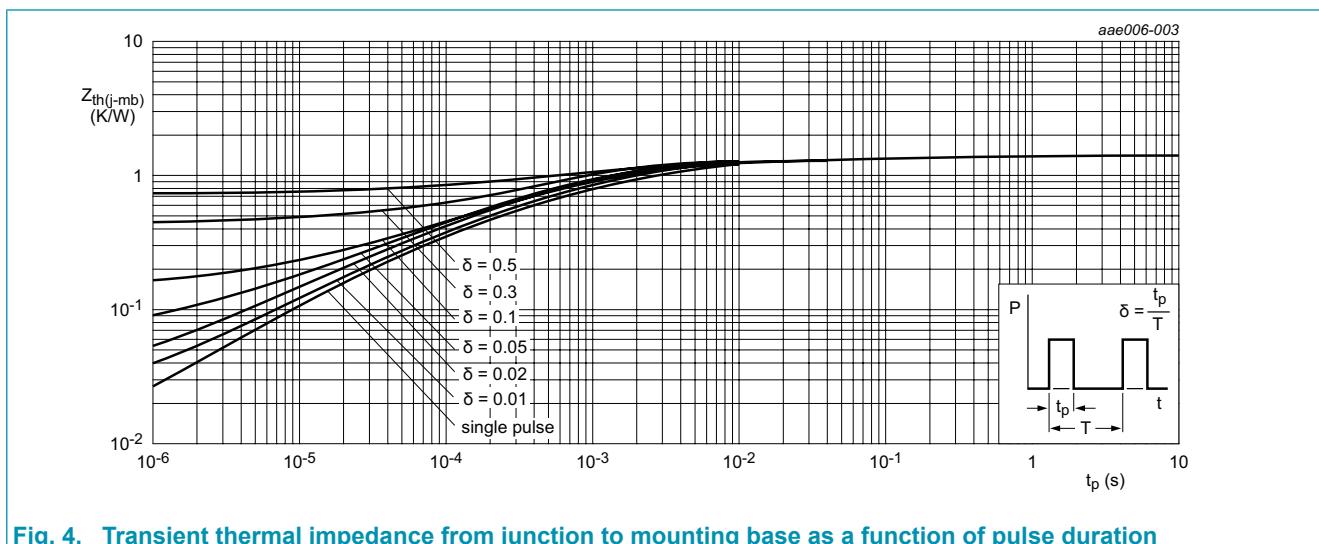
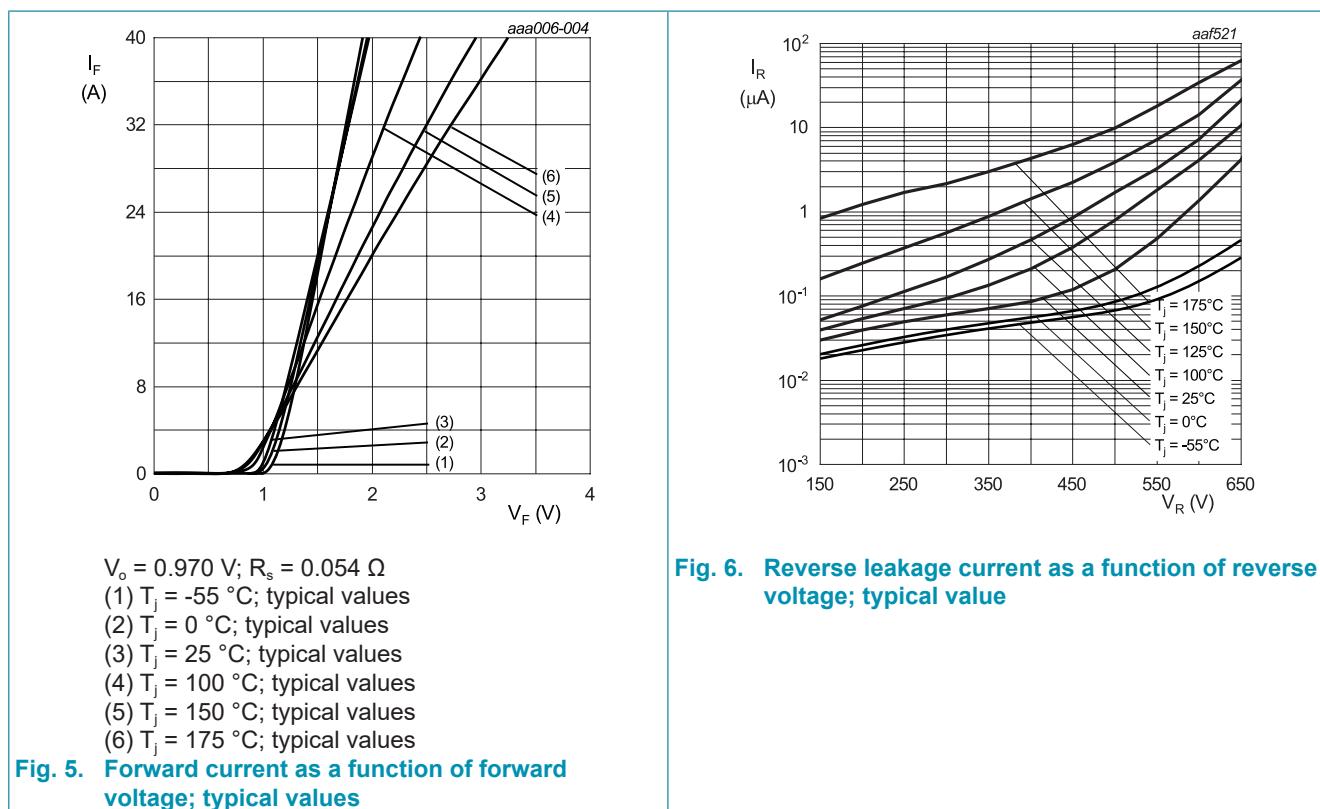


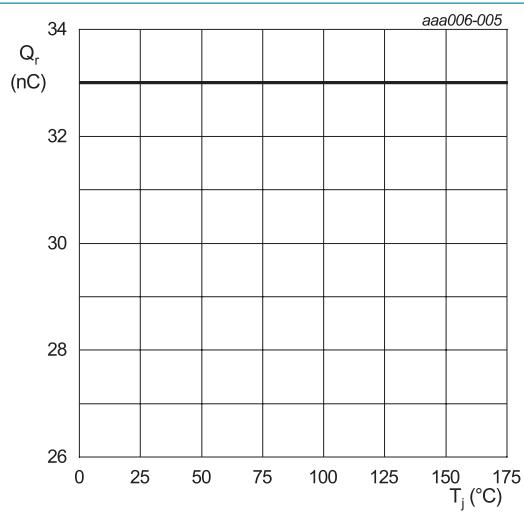
Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward current	$I_F = 20 \text{ A}; T_j = 25^\circ\text{C}$ ; Fig. 5		-	1.5	1.7	V
		$I_F = 20 \text{ A}; T_j = 150^\circ\text{C}$ ; Fig. 5		-	1.8	2.1	V
$I_R$	reverse current	$V_R = 650 \text{ V}; T_j = 25^\circ\text{C}$ ; Fig. 6		-	-	120	$\mu\text{A}$
		$V_R = 650 \text{ V}; T_j = 150^\circ\text{C}$ ; Fig. 6		-	-	480	$\mu\text{A}$
<b>Dynamic characteristics</b>							
$Q_r$	recovered charge	$I_F = 20 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s}$ ; $T_j = 25^\circ\text{C}$ ; Fig. 7		-	33	-	nC
$C_d$	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; T_j = 25^\circ\text{C}$		-	655	-	pF
		$f = 1 \text{ MHz}; V_R = 300 \text{ V}; T_j = 25^\circ\text{C}$		-	88	-	pF
		$f = 1 \text{ MHz}; V_R = 600 \text{ V}; T_j = 25^\circ\text{C}$		-	85	-	pF
$E_{as}$	non-repetitive avalanche energy	$I_R = 7.5 \text{ A}; L = 5 \text{ mH}; T_{j(\text{init})} = 25^\circ\text{C}$		150	-	-	mJ



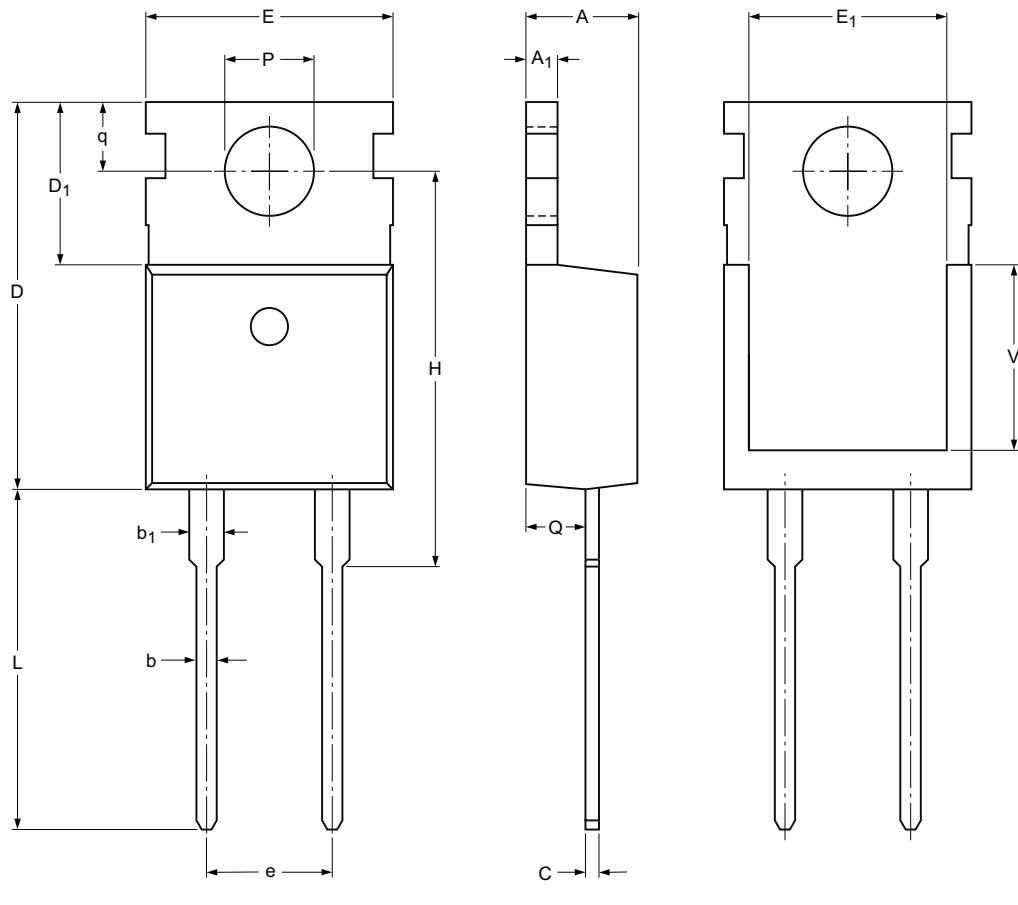


**Fig. 7. Recovered charge as a function of junction temperature**

## 11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC

SOD59A



Dimensions: (mm are the original dimensions)

0 5 10 mm  
scale

Unit	A	A <sub>1</sub>	b	b <sub>1</sub> <sup>(1)</sup>	c	D	D <sub>1</sub>	E	e	H	L	P	Q	q	E <sub>1</sub>	V
mm	max 4.7	1.40	0.95	1.70	0.65	15.8	6.8	10.30	5.08	16.25	15.0	3.80	2.6	2.95	8.1	6.9
	nom	4.3	1.15	0.70	1.17	0.45	15.6	6.4	9.65 (REF)	15.70	12.5	3.53	2.2	2.65	7.9	(REF)
	min	4.3	1.15	0.70	1.17	0.45	15.6	6.4	9.65 (REF)	15.70	12.5	3.53	2.2	2.65	7.9	(REF)

Note

1. Protruded dambar are included in the dimension.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD59A	TO-220AC (2-lead)				15-03-24 15-03-30

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